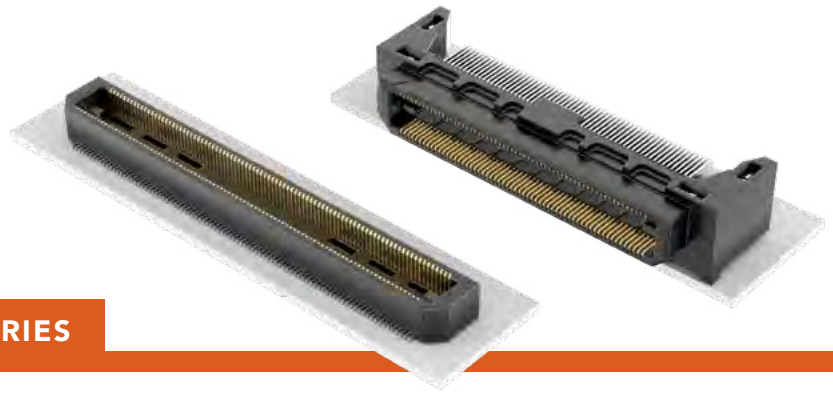


BASIC BLADE & BEAM HEADER

(0.50 mm) .0197" PITCH • BTH SERIES



BTH
Mates:
BSH

SPECIFICATIONS

Insulator Material:
Black LCP
Contact Material:
Phosphor Bronze
Plating:
Au or Sn over
50 μ" (1.27 μm) Ni
Current Rating:
2.0 A per pin
(2 pins powered)
Operating Temp Range:
-55 °C to +125 °C
Voltage Rating:
175 VAC
Max Cycles:
100

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
Vertical=
(0.10 mm) .004" max (030-090),
(0.15 mm) .006" max (120-150)*
Right-angle=
(0.15 mm) .006" max (030-090)*
*(.004" stencil solution
may be available; contact
IPG@samtec.com)
Board Stacking:
For applications requiring more
than two connectors per board
or 90 positions or higher,
contact ipg@samtec.com

ALSO AVAILABLE

MOQ Required

30 μ" (0.76 μm) Gold
Edge Mount Capability
8 mm, 11 mm, 16 mm,
19 mm and 22 mm Stack
Height (Caution: Some
automatic placement/
inspection machines may
have component height
restrictions. Please consult
machinery specifications.)
(11 mm, 16 mm, 19 mm
and 22 mm not available
with 50 positions)



Note:
Some lengths, styles and
options are non-standard,
non-returnable.

BTH	NO. OF POSITIONS PER ROW	01	PLATING OPTION	D	A	OTHER OPTION
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**-030, -050, -060,
-090, -120, -150**

-F
= Gold Flash
on contact,
Matte Tin on tail

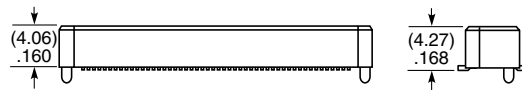
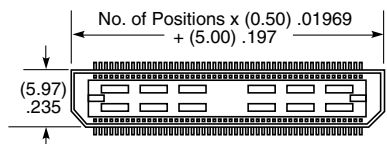
-L
= 10 μ" (0.25 μm)
Gold on contact,
Matte Tin on tail

-C*
= Electro-Polished Selective
50 μ" (1.27 μm) min
Au over 150 μ" (3.81 μm)
Ni on Signal Pins in contact
area, Matte Tin over
50 μ" (1.27 μm) min
Ni on all solder tails
(* -C Plating passes
10 year MFG testing)

-K
= (7.00 mm) .276"
DIA Polyimide
Film Pick
& Place Pad

-TR
= Tape & Reel
(120 positions
maximum)

-FR
= Full Reel
Tape & Reel
(must order
maximum
quantity per
reel; contact
Samtec for
quantity breaks)
(120 positions
maximum)



MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5.00 mm) .1971"

*Processing conditions will affect mated height.

BTH	NO. OF POSITIONS PER ROW	01	PLATING OPTION	D	RA	WT	OTHER OPTION
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-030, -060, -090

-F
= Gold Flash on
contact, Matte
Tin on tail

-L
= 10 μ" (0.25 μm)
Gold on contact,
Matte Tin on tail

-K
= (7.00 mm)
.276" DIA
Polyimide
Film Pick &
Place Pad

